

RoHS Compliant

APPROVAL SHEET

Issued No. : _____

DESCRIPTION : SMD 3225 CRYSTAL
NOMINAL FREQ. : 25.000000 MHz
TAITIEN P/N : 11345-X-002-3
TAITIEN MODEL : XXCCCLNANF-25.000000MHz
REVISION : 1
DATE : 06/28/2018

QA	Checked	Prepared
 數位簽署者 Monica Jiang DN : cn=Monica Jiang , c=<無> , o=QA , ou=QA , email=frijiang@taitien.com. tw 日期 : 2018.06.28 14:05:42 +08'00'	 數位簽署者 李成龍 DN : cn=李成龍 , c=<無> 無 日期 : 2018.06.28 13:18:12 +08'00'	 數位簽署者 WEIBO DN : cn=WEIBO , c=<無> > , o=QA , ou=QA 日期 : 2018.06.28 09:11:58 +08'00'

CUSTOMER : _____

CUSTOMER P/N : _____

Customer Signature
Approved:
Date:

CONTENT

SPECIFICATIONS	PAGE
ELECTRICAL SPECIFICATIONS	4~5
RECOMMENDED IR REFLOW PROFILE	6
PRODUCT DIMENSIONS	7
PRODUCT IDENTIFICATION (MARKING)	7
PACKAGE INFORMATION	8

ATTACHMENT

TESTING DATA	PAGE
ELECTRICAL CHARACTERISTICS TEST	9
OTHER DATA	
SUBSTANCE ANALYSIS LIST OF RAW MATERIAL	10

ELECTRICAL SPECIFICATIONS

	Parameter	Min.	Typ.	Max.	Units	Test Condition
1-1	Nominal Frequency	25.000000			MHz	
1-2	Frequency Tolerance.	-20		+20	ppm	at 25°C +/-2°C
1-3	Operating Temperature range	-40		+85	°C	
1-4	Storage Temperature range	-55		+125	°C	
1-5	Temperature Characteristics	-20		+20	ppm	-40°C to +85°C
1-6	Nominal Load Capacitance	10			pF	
1-7	Series Resistance			60	Ω	
1-8	Shunt Capacitance			3	pF	
1-9	Motion Capacitance				fF	
1-10	Motion Inductance				mH	
1-11	Q factor				K	
1-12	Spurious Response				dB	
1-13	Frequency Pull ability				ppm/pF	
1-14	C0/C1 Ratio					
1-15	Aging	-3		+3	ppm/year	
1-16	Insulation Resistance	500MΩ Min. @ DC100V				
1-17	Nominal Drive Level	10			μW	into 10Ω
1-18	Dependency Condition				μW	
1-19	Drive Level Dependency Resistance Max. Minus Min.				Ω	
1-20	Drive Level Dependency Frequency Max. Minus Min.				ppm	
1-21	Drive Level Dependency Resistance Max.				Ω	

■ CUSTOMER SPECIAL REQUIREMENT

2

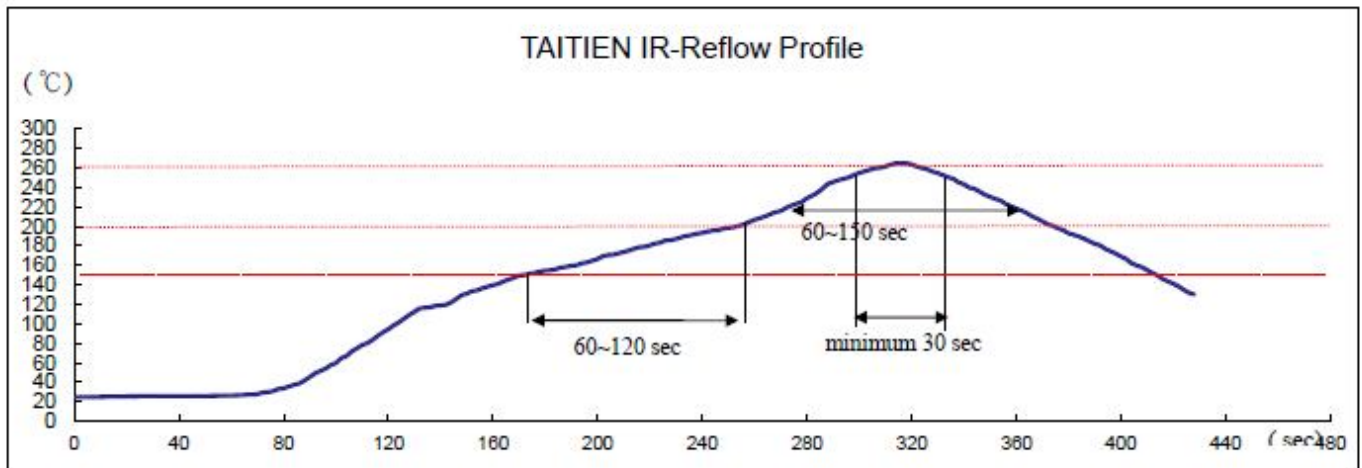
■ ENVIRONMENTAL

	Parameter	Reference Std.	Test Condition
3-1	Vibration Test	MIL-STD-883 2007 Condition A	10~2000Hz, 1.52mm, 20g, each axis for 4 hrs
		JESD22-B103 Condition 1	
3-2	Thermal Shock	MIL-STD-883 1010 Condition B	-55°C, 125°C; soak time is 10 mins, with total 200 cycles
		JESD22-A104 Condition B	
3-3	Mechanical Shock	MIL-STD-883 2002 Condition B	1500G, half-sine, 0.5ms, each axis for 3 times.
		JESD22-B104 Condition B	

RECOMMENDED IR REFLOW PROFILE

- IR REFLOW PROFILE OF CERAMIC SMD PRODUCTS FOR Pb FREE PROCESS

TAITIEN ELECTRONICS CO., LTD.



Reference Standard: JEDEC-STD 020

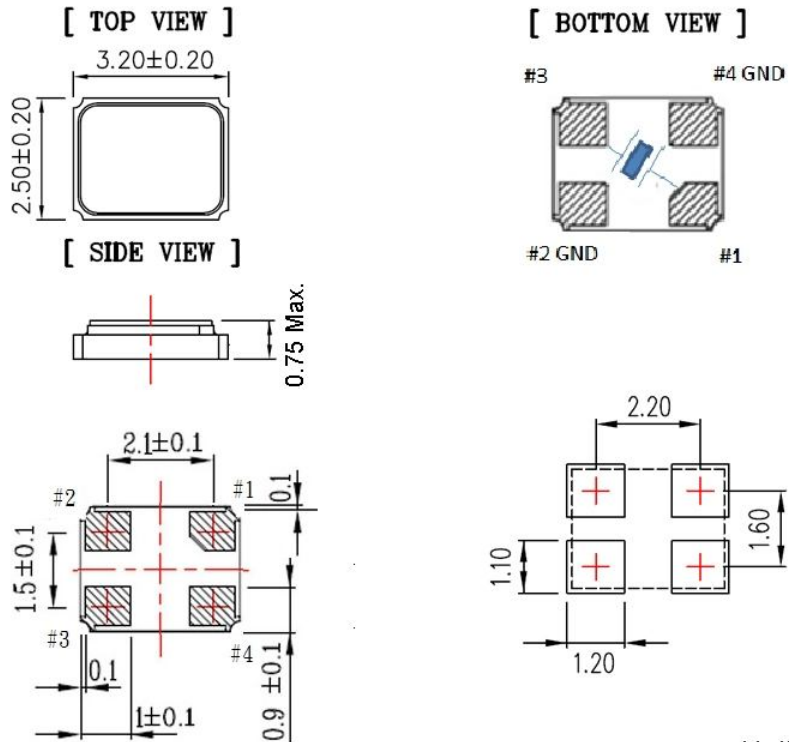
Test conditions: Pre-heating : 150°C to 200°C, 60~120secs.

Heating : 217°C, 60~150sec.

Peak temperature at least : 260°C, The time above 255 °C : minimum 30sec.

■ PRODUCT DIMENSIONS

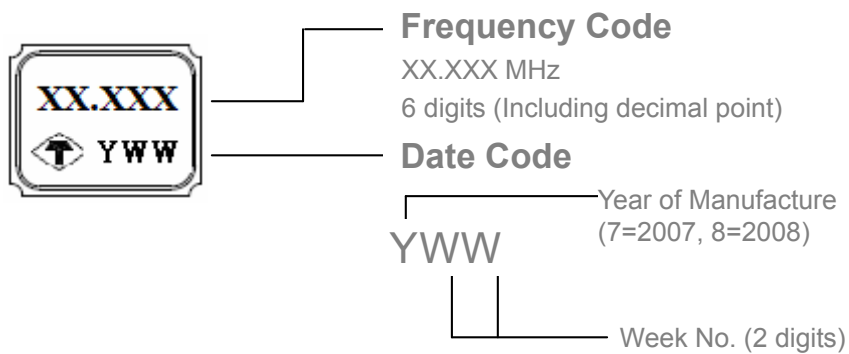
➤ DIMENSIONS



Unit:mm

■ PRODUCT IDENTIFICATION (MARKING)

➤ PROCEDURE: LASER

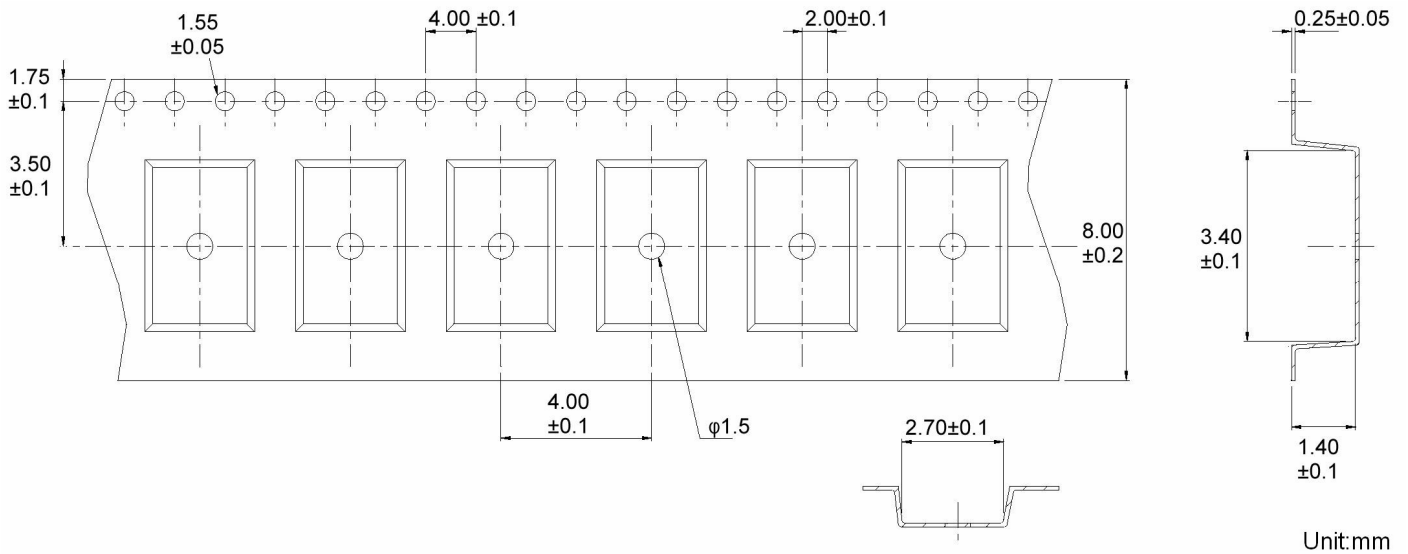


➤ FOR EXAMPLE:



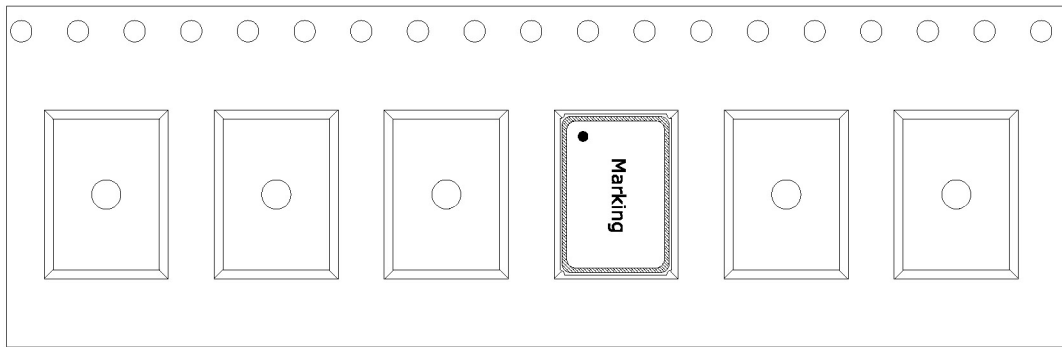
PACKAGE INFORMATION

TAPE (CARRIER) DIMENSIONS

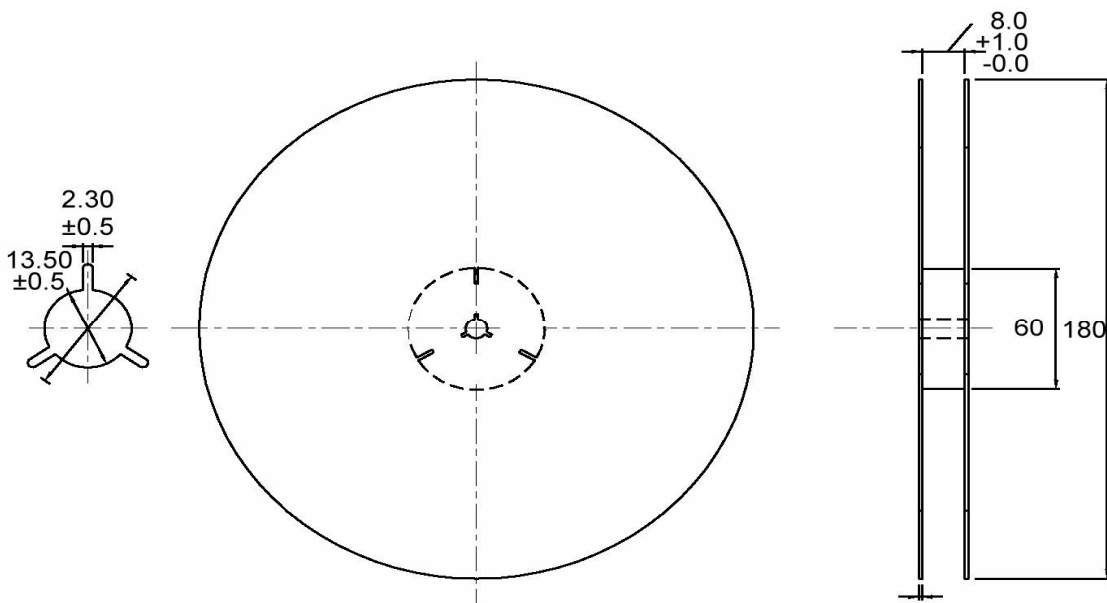


Unit:mm

THE DIRECTION OF PACKING



REEL DIMENSIONS



Unit:mm

ATTACHMENT

ELECTRICAL CHARACTERISTICS TEST

EXCEL EXPORT PRINTOUT FORMAT

Batch # : Test on :06/28/2018
 Setup file : 2500000010
 Taitien Spec NO. : 11345X0023
 Description :
 Ref. Freq. : 25.000000MHz
 Power : 10 Uw INTO 10 ohm
 Search range : 1000 ppm
 Mode Type : Fundamental AT
 Spurious Response:
 Timebase : Internal

	Status	FL:10+/- 0.0pF	FL1:10+/- 0.0pF	Rr	C0	C1	C0/C1	Ts	Q	L	FOLD	DLD2	RLD2
	Unit	[MHz]	[ppm]	[ohm]	[pF]	[fF]		[ppm/pF]	[K]	[mH]	ppm	Ohms	Ohms
	Center	25.000000	0	/	/	/	/	/	/	/	/	/	/
	High	25.000500	20	60	3	9999.9	9999.9	9999.9	9999.9	9999.9	9999.9	9999.9	9999.9
	Low	24.999500	-20	0	0	0	0	0	0	0	0	0	0
1	Pass 1	24.999818	-7.3	7.7	0.8	3.9	202.0	16.6	215.4	10.5	1.0	3.3	10.8
2	Pass 1	24.999778	-8.9	8.0	0.8	3.8	204.0	16.4	208.7	10.7	1.5	0.4	8.2
3	Pass 1	24.999768	-9.3	8.8	0.8	3.7	244.0	13.7	227.0	12.8	1.5	0.5	9.3
4	Pass 1	24.999923	-3.1	8.5	0.8	3.7	214.0	16.0	199.4	10.8	1.5	0.2	8.5
5	Pass 1	24.999908	-3.7	9.3	0.8	3.7	228.0	15.1	193.4	11.5	1.4	0.4	9.7
6	Pass 1	24.999835	-6.6	7.3	0.8	3.6	223.0	15.6	239.4	11.1	1.6	0.5	7.7
7	Pass 1	24.999903	-3.9	5.9	0.8	3.6	221.0	15.5	297.5	11.2	1.9	0.6	6.3
8	Pass 1	24.999880	-4.8	7.0	0.8	3.8	210.0	16.4	238.1	10.6	1.8	0.5	7.2
9	Pass 1	24.999883	-4.7	10.4	0.8	3.6	219.0	15.6	168.6	11.1	1.7	0.5	10.6
10	Pass 1	24.999890	-4.4	12.7	0.8	3.9	205.0	16.6	129.5	10.5	1.4	4.4	13.0
	Average	24.999858	-5.7	8.6	0.8	3.7	217.0	15.8	211.7	11.1	1.5	1.1	9.1
	Stdev	0.000055	2.21	1.92	0.01	0.12	12.92	0.89	44.95	0.69	0.25	1.46	1.98
	CA	-28.35	-28.35	/	/	/	/	/	/	/	/	/	/
	CP	3.01	3.01	8.92	62.37	/	/	/	/	/	/	/	/
	CPK	2.16	2.16	8.92	62.37	/	/	/	/	/	/	/	/

Supervisor: 李成龍
 數位簽署者 李成龍
 DN : cn=李成龍,
 c=<無>
 日期 : 2018.06.28
 13:49:42 +08'00'

Inspector: WEIBO
 數位簽署者 WEIBO
 DN : cn=WEIBO, c=<無>,
 o=QA, ou=QA
 日期 : 2018.06.28
 09:12:09 +08'00'

ATTACHMENT

SUBSTANCE ANALYSIS LIST OF RAW MATERIAL



TAITIEN ELECTRONICS CO.,LTD.

TAITIEN ELECTRONICS (NANJING) CO.,LTD.
 原材料有害物質成分分解表(Hazardous Substance Analysis List of Raw Material)

型號(Model): XX type

重量(weight): 19.36 mg +/-20%

No.	Name of Part	Material Name	Material Mass(mg)	Constituent name	CAS No.	Material Mass(mg)	Material Analysis(%)	Supplier Name	檢驗机构 Test institution	檢測報告編號 Test report No.	送檢日期Test date	有害物質或元素的含量 (ppm) Hazardous substances content														檢測報告 inspection report	
												ROHS										Halogen		PFOS	PFOA		
												Pb	Cd	Hg	Cr6+	PBBs	PBDEs	DBP	BBP	DEHP	DIBP	Br	Cl				
1	Base	Ceramic	8.63	A2O3	1344-28-1	7.7670	90.00	Kyocera	CTI	A2180082952101001	2018/5/11	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND		
				Cr2O3	1308-38-9	0.1726	2.00																				
				Mo	7439-98-7	0.1726	2.00																				
				SiO2	14808-80-7	0.5178	6.00																				
		Metalizing	2.99	W	7440-33-7	2.9900	100.00			A2180082952101005	2018/5/11	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND		
		Plate-Au	0.12	Au	7440-57-5	0.1200	100.00			A2180082952101003	2018/5/11	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	
		Plate-Ni	0.42	Ni	7440-02-0	0.4200	100.00			A2180082952101004	2018/5/11	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	
		Seal Ring	2.24	Co	7440-48-4	0.4032	18.00			A2180082952101006	2018/5/11	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	
				Fe	7439-89-6	1.1672	53.00																				
				Ni	7440-02-0	0.6496	29.00																				
Solder	0.56	Ag	7440-22-4	0.3976	71.00	A2180082952101006	2018/5/11	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND					
		Cu	7440-50-8	0.1624	29.00																						
2	Lid	Kovar	3.2	Fe	7439-89-6	1.73	54	JingSai	SGS	SHAEC1724751903	2017/11/15	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND			
				Ni	7440-02-0	0.93	29																				
				Co	7440-48-4	0.54	17																				
		Plating	0.3	Ni	7440-02-0	0.3	100			CE/2017/A1761	2017/10/19	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND			
3	Adhesive	Silver paste	0.6	Ag	7440-22-4	0.48	80	THREE BOND	SGS	CE/2018/40773 CE/2018/40774 CE/2018/40776 CE/2018/24247	2018/4/16 2018/4/16 2018/4/16 2018/3/2	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND			
				SiO2	14808-80-7	0.06	10																				
				Silicone Resin	63146-82-9	0.06	10																				
4	Blank	Quartz	0.5	SiO2	14808-80-7	0.5	100	TAITIEN(SZ)	SGS	CANEC1719620101 CANEC1719620102 CANEC1719620103	2017/10/17 2017/10/17 2017/10/17	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND			
				Cr	0.01	Cr	7440-47-3					0.01	100	SHAEC1717528901	2017/8/15	9	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND
5	Electrode	Cr	0.01	Cr	7440-47-3	0.01	100	SOLAR	SGS	SHAEC1717528901	2017/8/15	9	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND			
		Ag	0.09	Ag	7440-22-4	0.09	100					SHAEC1716785601	2017/8/7	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	ND	

19/36

QC0706-03FN-1.0